

General Description

SFGMOS[®] MOSFET is based on Oriental Semiconductor's unique device design to achieve low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. The low V_{th} series is specially designed to use in synchronous rectification power systems with low driving voltage.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery



Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switched mode power supply

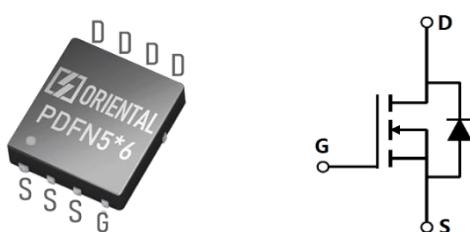
Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	100	V
$I_D, pulse$	180	A
$R_{DS(ON) max} @ V_{GS}=10V$	10	mΩ
Q_g	28.9	nC

Marking Information

Product Name	Package	Marking
SFG10S10GF	PDFN5*6	SFG10S10G

Package & Pin information



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	100	V
Gate source voltage	V_{GS}	± 20	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	60	A
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D,\text{pulse}}$	180	A
Continuous diode forward current ¹⁾ , $T_C=25^\circ\text{C}$	I_S	60	A
Diode pulsed current ²⁾ , $T_C=25^\circ\text{C}$	$I_{S,\text{Pulse}}$	180	A
Power dissipation ³⁾ , $T_C=25^\circ\text{C}$	P_D	107	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	65	mJ
Operation and storage temperature	T_{stg}, T_j	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	1.17	$^\circ\text{C}/\text{W}$
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$

Electrical Characteristics at $T_j=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	100			V	$V_{GS}=0 \text{ V}, I_D=250 \mu\text{A}$
Gate threshold voltage	$V_{GS(\text{th})}$	1.5		2.5	V	$V_{DS}=V_{GS}, I_D=250 \mu\text{A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		9	10	$\text{m}\Omega$	$V_{GS}=10 \text{ V}, I_D=30 \text{ A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		12	14	$\text{m}\Omega$	$V_{GS}=4.5 \text{ V}, I_D=12 \text{ A}$
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=20 \text{ V}$
				-100		$V_{GS}=-20 \text{ V}$
Drain-source leakage current	I_{DSS}			1	μA	$V_{DS}=100 \text{ V}, V_{GS}=0 \text{ V}$
Gate resistance	R_G		5.5		Ω	$f=1 \text{ MHz}, \text{Open drain}$

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		1998		pF	V _{GS} =0 V, V _{DS} =50 V, f=100 kHz
Output capacitance	C _{oss}		322		pF	
Reverse transfer capacitance	C _{rss}		7.1		pF	
Turn-on delay time	t _{d(on)}		22.1		ns	V _{GS} =10 V, V _{DS} =50 V, R _G =2 Ω, I _D =25 A
Rise time	t _r		5.2		ns	
Turn-off delay time	t _{d(off)}		44		ns	
Fall time	t _f		8.4		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q _g		28.9		nC	V _{GS} =10 V, V _{DS} =50 V, I _D =25 A
Gate-source charge	Q _{gs}		6		nC	
Gate-drain charge	Q _{gd}		6.8		nC	
Gate plateau voltage	V _{plateau}		3.7		V	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V _{SD}			1.3	V	I _S =30 A, V _{GS} =0 V
Reverse recovery time	t _{rr}		103		ns	V _R =50 V, I _S =25 A, di/dt=100 A/μs
Reverse recovery charge	Q _{rr}		379		nC	
Peak reverse recovery current	I _{rrm}		6.4		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=30 V, V_{GS}=10 V, L=0.3 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams

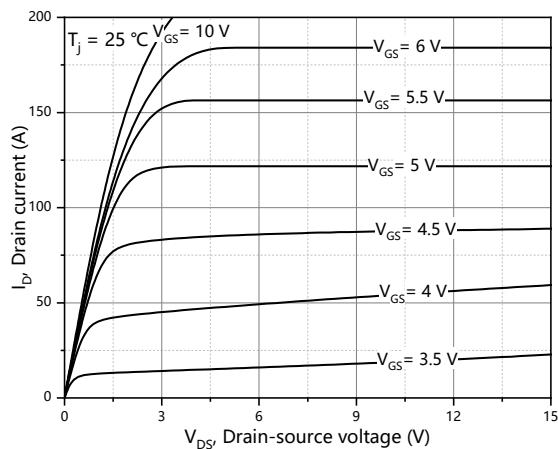


Figure 1. Typ. output characteristics

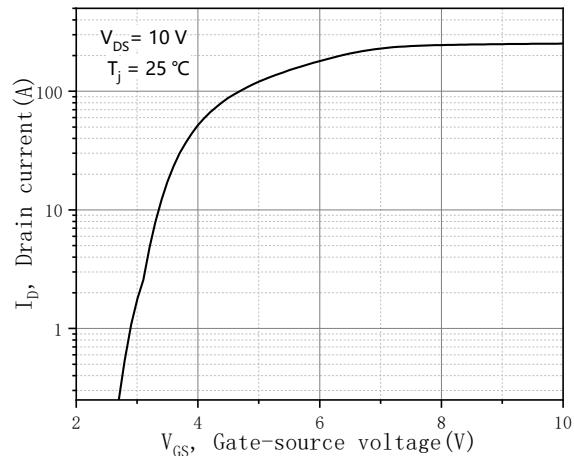


Figure 2. Typ. transfer characteristics

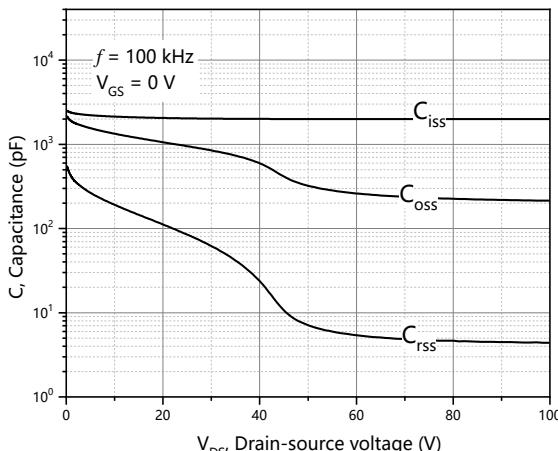


Figure 3. Typ. capacitances

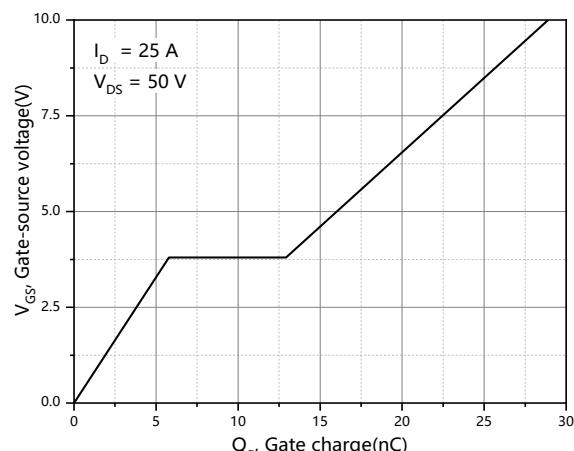


Figure 4. Typ. gate charge

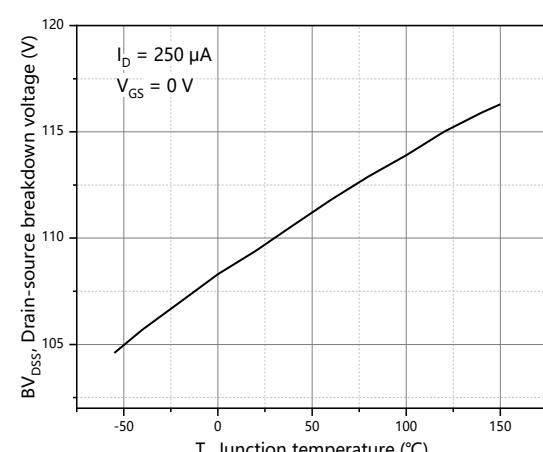


Figure 5. Drain-source breakdown voltage

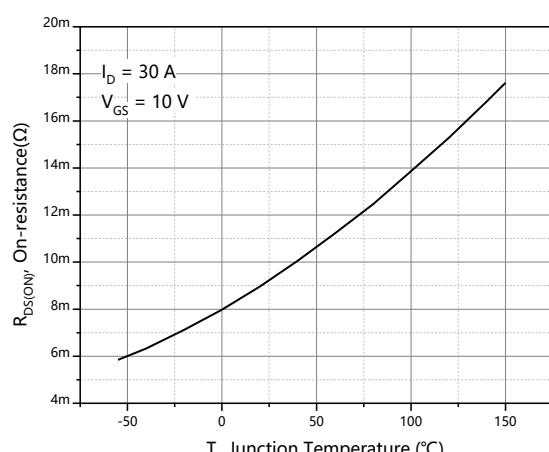


Figure 6. Drain-source on-state resistance

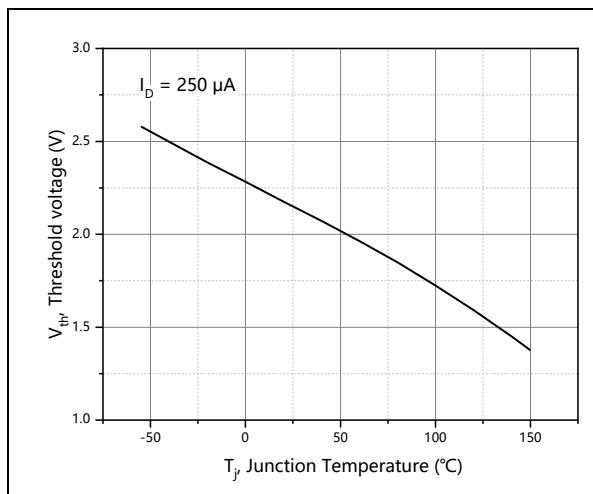


Figure 7. Threshold voltage

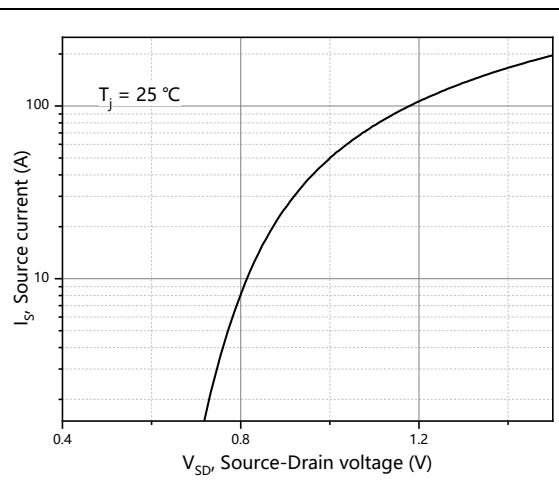


Figure 8. Forward characteristic of body diode

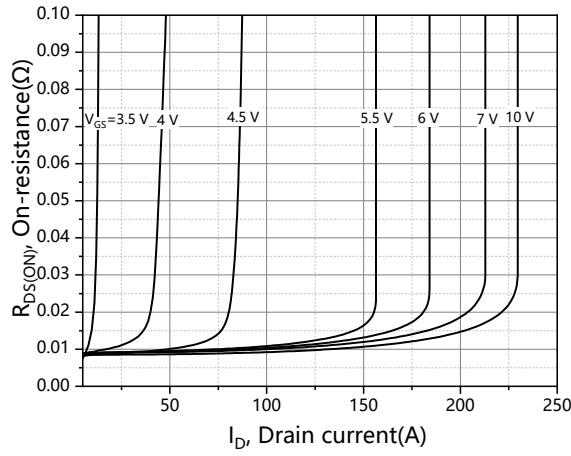


Figure 9. Drain-source on-state resistance

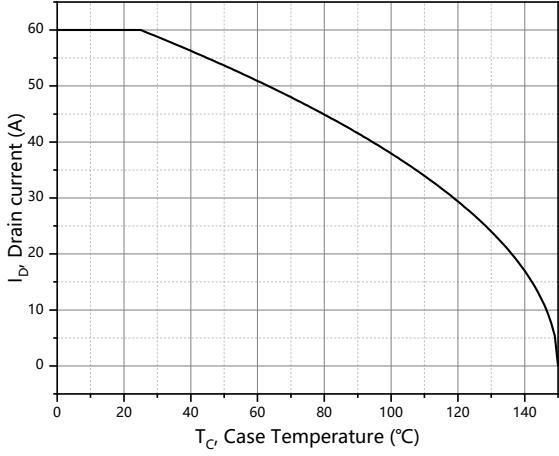


Figure 10. Drain current

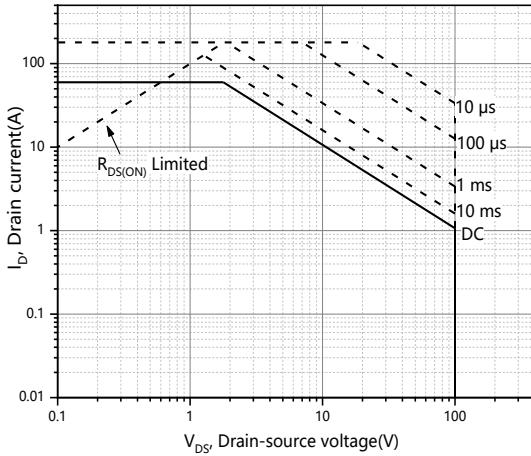


Figure 11. Safe operation area $T_C=25^\circ\text{C}$

Test circuits and waveforms

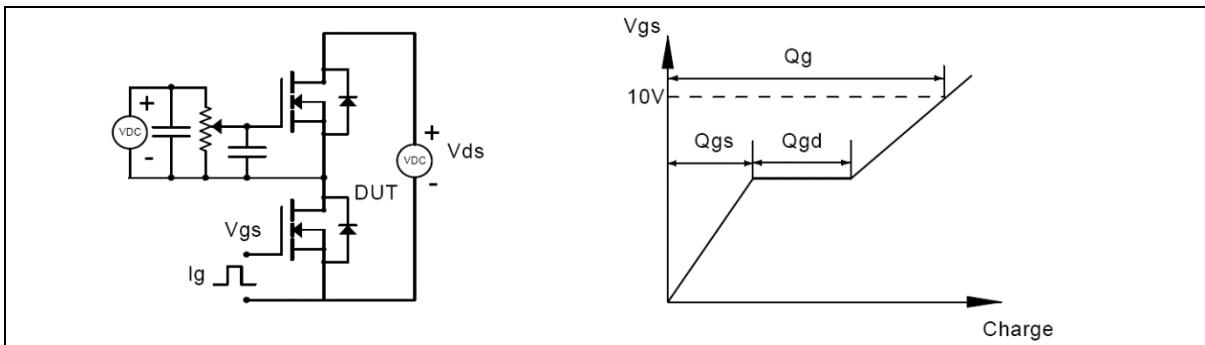


Figure 1. Gate charge test circuit & waveform

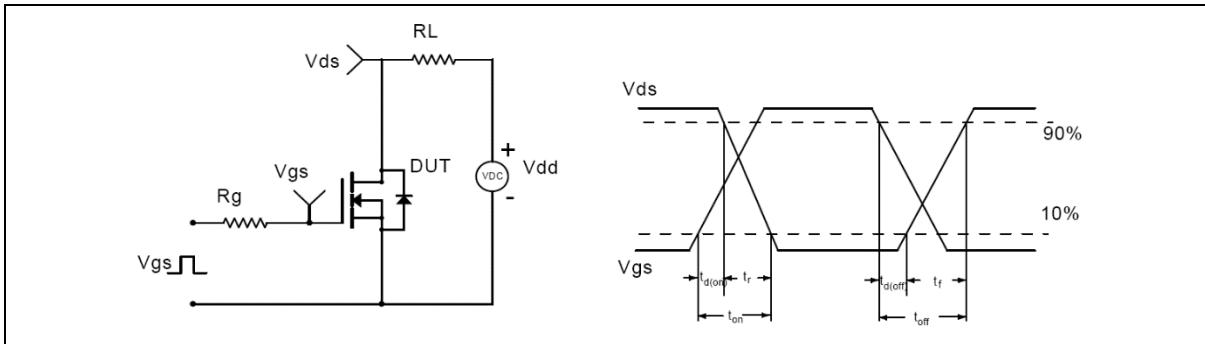


Figure 2. Switching time test circuit & waveforms

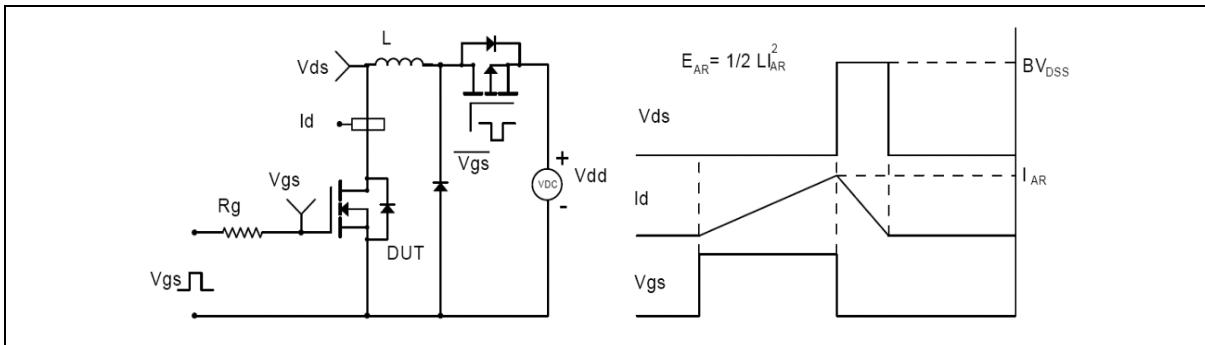


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

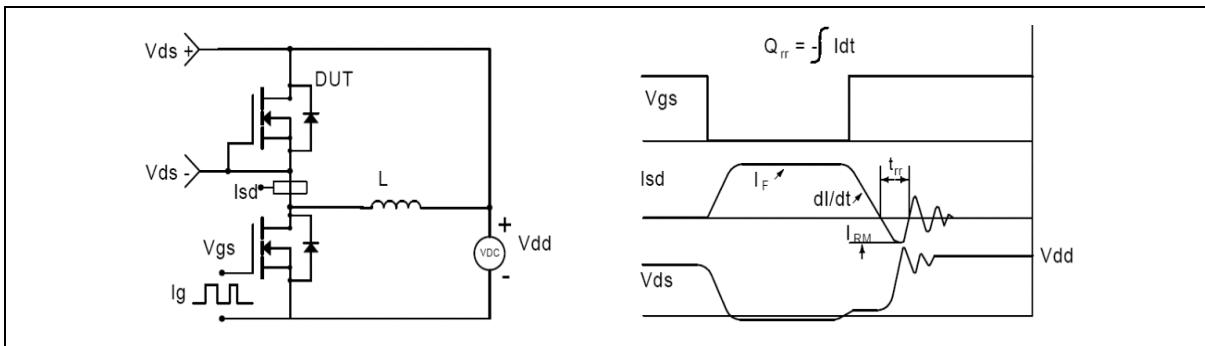
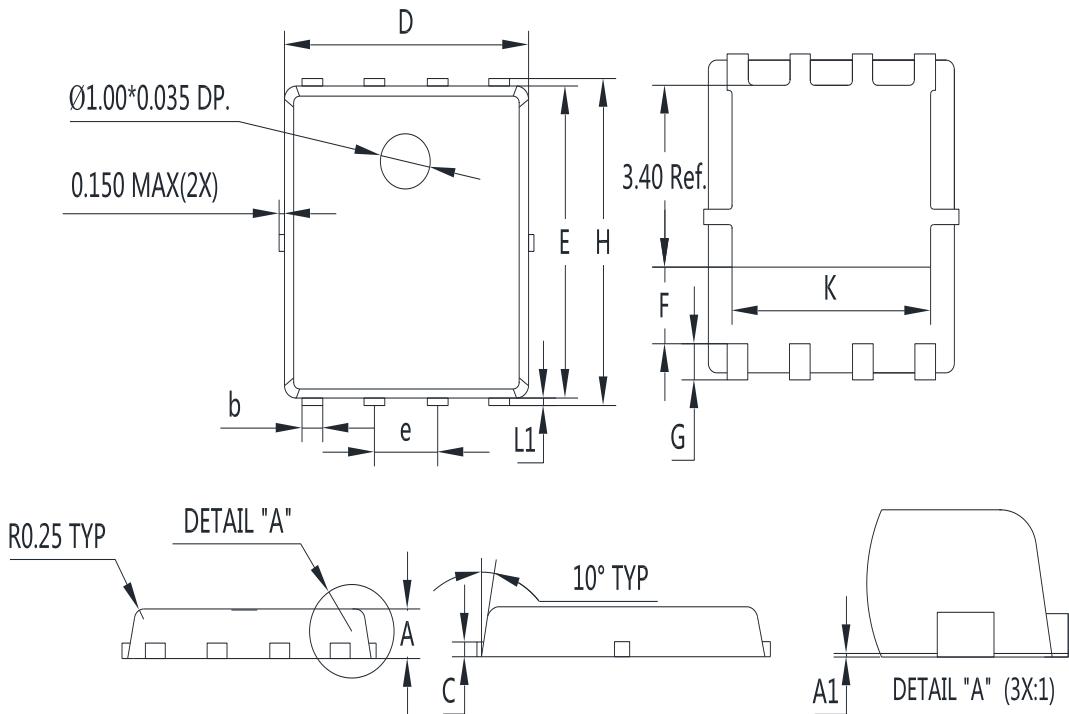


Figure 4. Diode reverse recovery test circuit & waveforms

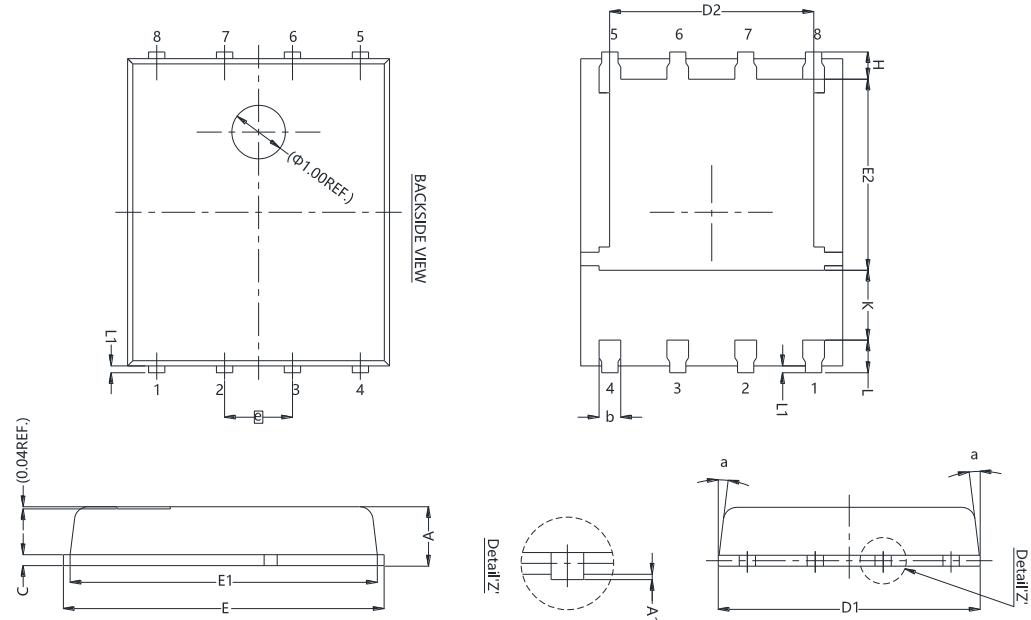
Package Information



Symbol	mm		
	Min	Nom	Max
A	0.8	0.9	1.0
A1	0	0.03	0.05
b	0.35	0.42	0.49
c	0.254 REF		
D	4.9	5.0	5.1
F	1.40 REF		
E	5.7	5.8	5.9
e	1.27 BSC		
H	5.95	6.08	6.20
L1	0.10	0.14	0.18
G	0.60 REF		
K	4.00 REF		

Version 1: PDFN5*6-K package outline dimension

Package Information



Symbol	mm		
	Min	Nom	Max
A	0.90	1.00	1.10
A1	0.00	-	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
a	0°	-	12°

Version 2: PDFN5*6-M package outline dimension

Ordering Information

Package Type	Units/Reel	Reels / Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
PDFN5*6-K	5000	2	10000	5	50000
PDFN5*6-M	5000	2	10000	5	50000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFG10S10GF	PDFN5*6	yes	yes	yes

Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Oriental Semiconductor hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

For further information on technology, delivery terms and conditions and prices, please contact the Oriental Semiconductor sales representatives (www.orientalsemi.com).

© Oriental Semiconductor Co.,Ltd. All Rights Reserved /